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Ultratech Receives Follow-On, Multiple System Orders From World's Leading OSATs For Advanced Packaging Applications

Ultratech's AP300E Lithography Systems will be used for Next-generation, High-volume, Flip-Chip and Wafer-level Packaging Applications

SAN JOSE, Calif., March 28, 2017 /PRNewswire/ -- **Ultratech, Inc.** (Nasdaq: UTEK), a leading supplier of lithography, laser processing and inspection systems used to manufacture semiconductor devices and high-brightness LEDs (HBLEDs), as well as atomic layer deposition (ALD) systems, today announced that it has received follow-on, multiple system orders from several outsourced semiconductor assembly and test (OSAT) companies in Taiwan, Korea and China. The AP300E lithography stepper will be used for leading-edge copper pillar and wafer-level packaging (WLP) in high-volume manufacturing (HVM). Ultratech plans to begin shipping the systems in Q2 and Q3 of this year.

Ultratech General Manager and Vice President of Lithography Products Rezwan Lateef stated, "OSATs are rapidly expanding their advanced packaging capabilities to capture the strong demand for copper pillar and fan-out package solutions. These customers look to their equipment suppliers to provide highly reliable, flexible, extendible and cost-effective solutions coupled with excellent application-specific knowledge. The AP300E lithography stepper delivers on all these aspects coupled with outstanding regional support. Ultratech believes that success in the OSAT market requires local, on-site support and has greatly expanded its presence (both in personnel and infrastructure) in the Asia Pacific region with a focus on Taiwan, China and Korea. These repeat, multiple system orders across the broad OSAT spectrum are a clear validation of our market leadership position and a strong statement of continued partnership from our customers. We look forward to working with these valued customers to meet their current production needs and to develop the applications of tomorrow."

Ultratech's AP300 Family of Lithography Steppers

The AP300 family of lithography systems is built on Ultratech's customizable Unity Platform™, delivering superior overlay, resolution and side wall profile performance and enabling highly-automated and cost-effective manufacturing. These systems are particularly well suited for copper pillar, fan-out, through-silicon via (TSV) and silicon interposer applications. In addition, the platform has numerous application-specific product features to enable next-generation packaging techniques, such as Ultratech's award winning dual-side alignment (DSA) system, utilized around the world in volume production.

Safe Harbor

This release includes forward looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Forward looking statements can generally be identified by words such as "anticipates," "expects," "remains," "thinks," "intends," "believes," "estimates," and similar expressions and include management's current expectation of its longer term prospects for success. These forward looking statements are based on our current expectations, estimates, assumptions and projections about our business and industry, and the markets and customers we serve, and they are subject to numerous risks and uncertainties that may cause these forward looking statements to be inaccurate. Such risks and uncertainties include the timing and possible delays, deferrals and cancellations of orders by customers; quarterly revenue fluctuations; industry and sector cyclicalities, instability and unpredictability; market demand for consumer devices utilizing semiconductors produced by our clients; our ability to manage costs; new product introductions, market acceptance of new products and enhanced versions of our existing products; reliability and technical acceptance of our products; our lengthy sales cycles, and the timing of system installations and acceptances; lengthy and costly development cycles for laser processing and lithography technologies and applications; competition and consolidation in the markets we serve; improvements, including in cost and technical features, of competitors' products; rapid technological change; pricing pressures and product discounts; our ability to collect receivables; customer and product concentration and lack of product revenue diversification; inventory obsolescence; general economic, financial market and political conditions and other factors outside of our control; domestic and international tax policies; cybersecurity threats in the United States and globally that could impact our industry, customers, and technologies; and other factors described in our SEC reports including our Annual Report on Form 10K filed for the year ended December 31, 2016. Due to these and other factors, the statements, historical results and percentage relationships set forth herein are not necessarily indicative of the results of operations for any future period. We undertake no obligation to revise or update any forward looking statements to reflect any event or circumstance that may arise after the date of this release.

About Ultratech: Ultratech, Inc. (Nasdaq: UTEK) designs, builds and markets manufacturing systems for the global technology industry. Founded in 1979, Ultratech serves three core markets: frontend semiconductor, backend semiconductor, and nanotechnology. The company is the leading supplier of lithography products for bump packaging of

integrated circuits and high brightness LEDs. Ultratech is also the market leader and pioneer of laser spike anneal technology for the production of advanced semiconductor devices. In addition, the company offers solutions leveraging its proprietary coherent gradient sensing (CGS) technology to the semiconductor wafer inspection market and provides atomic layer deposition (ALD) tools to leading research organizations, including academic and industrial institutions. Visit Ultratech online at: www.ultratech.com.
(UTEKG)

Unity Platform is a trademark of Ultratech, Inc.

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